

ABSTRACT

A probe apparatus includes a mounting member on which
an object to be inspected is mounted and a temperature
5 thereof is being adjusted, a probe card arranged opposite to
the mounting member, a driving mechanism which changes a
relative positional relationship between the mounting member
and the probe card, and a sensor which detects the distance
between the sensor and the probe card. By way of detecting
10 the height of the deformed probe card through the use of the
sensor and revising the elevation distance of the mounting
member, the electrode pads of the wafer W and the probe pins
can electrically contact each other with a stable pin
pressure, providing high inspection reliability and an
15 increase in throughput.